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Vishay Siliconix

Automotive Dual N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.064			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.082			
I _D (A) per leg	6			
Configuration	Dual			
Package	SO-8			

FEATURES

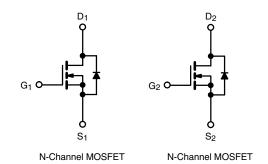
- TrenchFET® power MOSFET
- 100 % R_g and UIS tested
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





ROHS COMPLIANT HALOGEN FREE





ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V _{DS}	60	V		
Gate-Source Voltage	V_{GS}	± 20	V		
Continuous Drain Current	T _C = 25 °C		5.4		
Continuous Drain Current	T _C = 125 °C	- I _D	3.1		
Continuous Source Current (Diode Conduction) a	I _S	3.6	Α		
Pulsed Drain Current ^b		I _{DM}	21.5		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	8.5		
Single Pulse Avalanche Energy	L = 0.1 IIII1	E _{AS}	3.6	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	D	4	W	
	T _C = 125 °C	P_D	1.3	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	112	°C/W	
Junction-to-Foot (Drain)			38	C/VV	

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).



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PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static					l		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 20 V	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 60 V, T _J = 125 °C	-	-	50	μA
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 \text{ V}$	20	-	-	Α
		V _{GS} = 10 V	I _D = 3.4 A	-	0.045	0.064	
Drain Source On State Begintenes	В	V _{GS} = 10 V	I _D = 3.4 A, T _J = 125 °C	-	-	0.110	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.4 A, T _J = 175 °C	-	-	0.137	
		V _{GS} = 4.5 V	I _D = 3.7 A	-	0.060	0.082	
Forward Transconductance f	9fs	V _{DS} = 15 V, I _D = 3.7 A		-	12	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	375	470	pF
Output Capacitance	Coss	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	70	88	
Reverse Transfer Capacitance	C _{rss}			-	30	36	
Total Gate Charge ^c	Qg			-	8	12	
Gate-Source Charge ^c	Q_{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 4.3 \text{ A}$	1	1.2	1.5	nC
Gate-Drain Charge ^c	Q_{gd}			-	1.7	2.6	
Gate Resistance	R_g	f = 1 MHz		1.1	-	6.66	Ω
Turn-On Delay Time ^c	t _{d(on)}				6	9	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_L = 8.8 \ \Omega$ $I_D \cong 3.4 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \ \Omega$		-	2.8	4.2	ns
Turn-Off Delay Time ^c	t _{d(off)}			-	17	26	
Fall Time ^c	t _f			-	1.7	3	
Source-Drain Diode Ratings and Chara	cteristics ^b					_	
Pulsed Current ^a	I _{SM}			-	-	21.5	Α
Forward Voltage	V_{SD}	I _F = 2 A, V _{GS} = 0 V		-	0.75	1.1	V

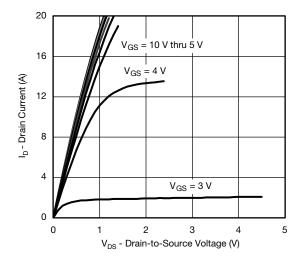
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

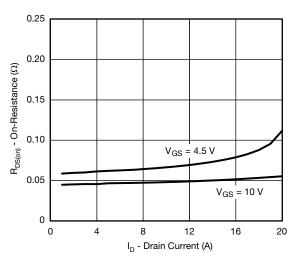
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



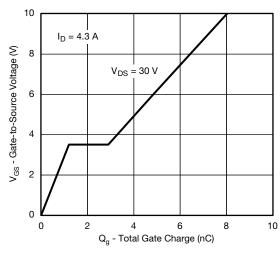
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



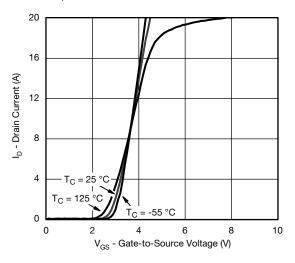
Output Characteristics



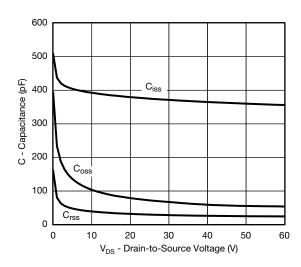
On-Resistance vs. Drain Current



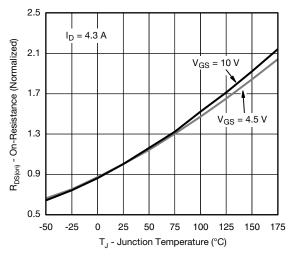
Gate Charge



Transfer Characteristics



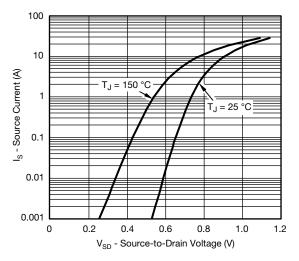
Capacitance



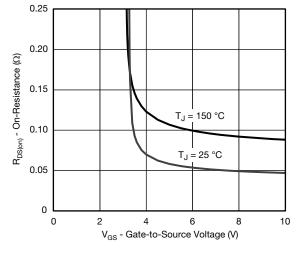
On-Resistance vs. Junction Temperature



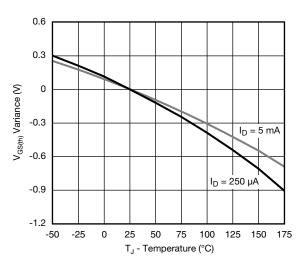
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



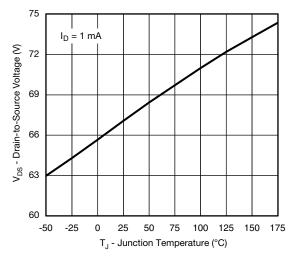
Source Drain Diode Forward Voltage



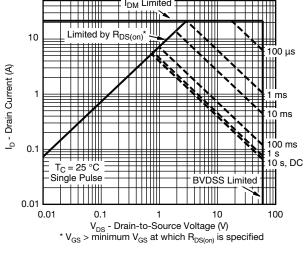
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

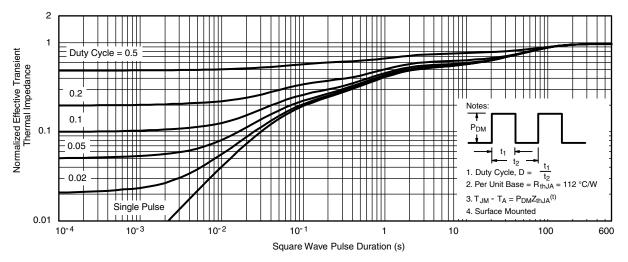


Drain Source Breakdown vs. Junction Temperature

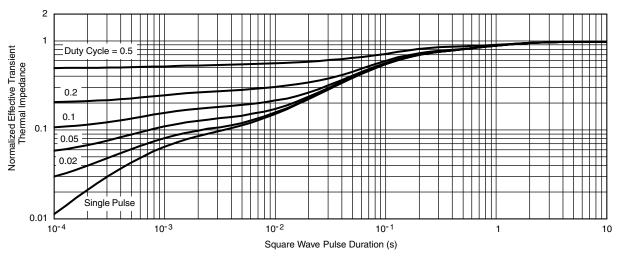




THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?71504.



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REVISION HISTORY a				
REVISION	DATE	DESCRIPTION OF CHANGE		
D	04-Aug-15	Revised R _g minimum limit		

Note

a. As of April 2014



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS IN			CHES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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